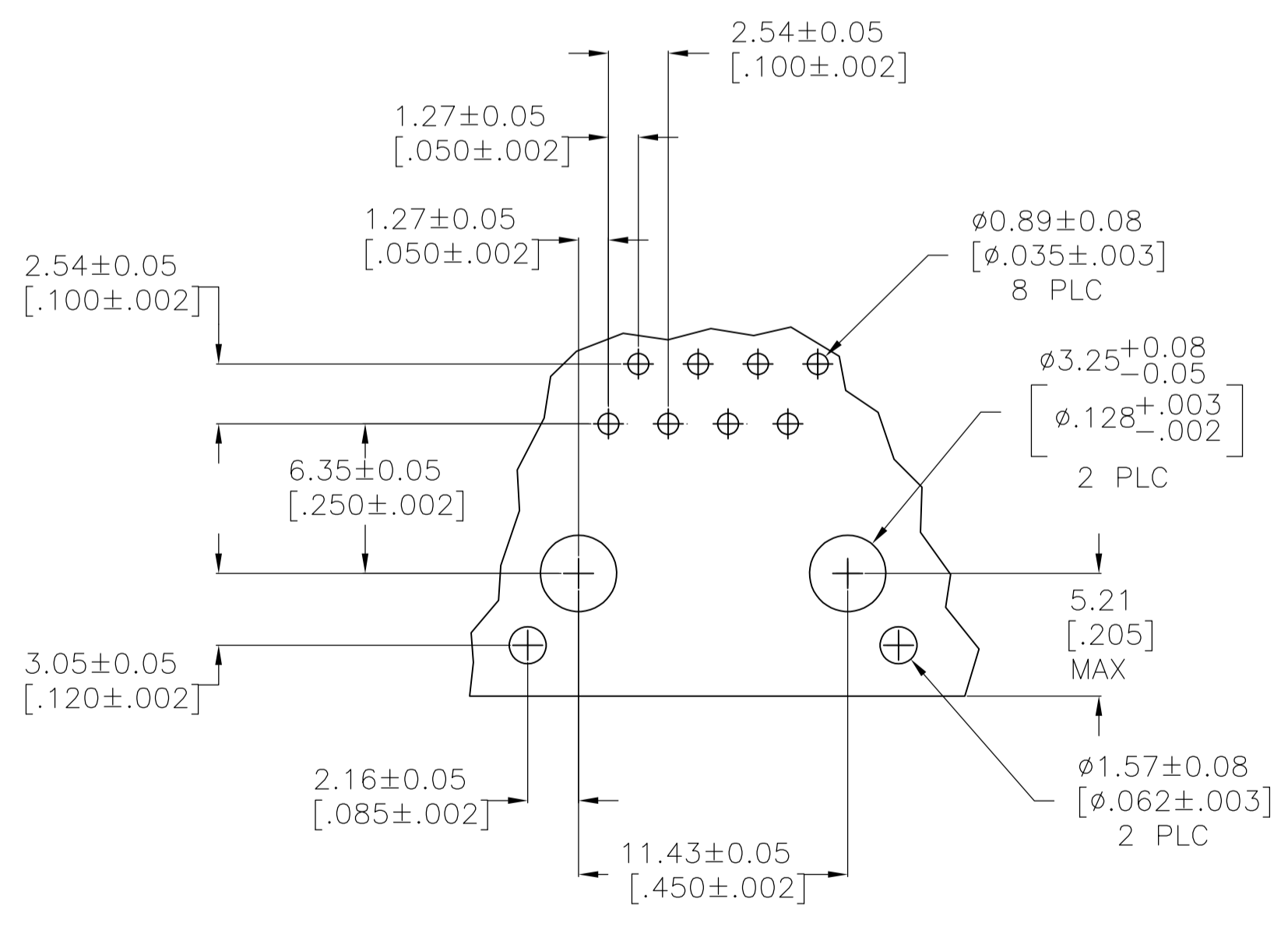
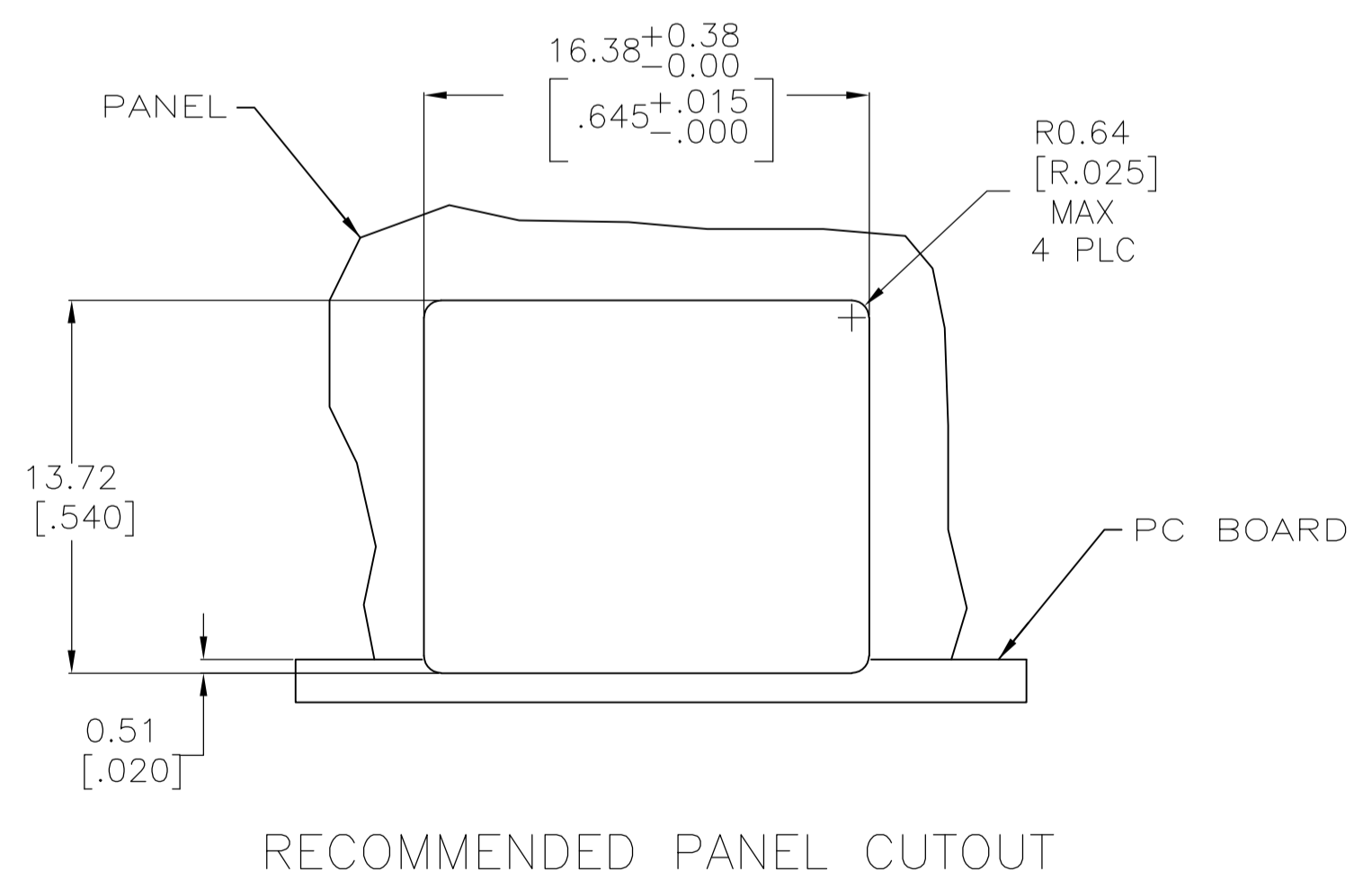


1. MATERIAL:
 HOUSING (SEE TABLE) - COLOR: BLACK
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27 μ m [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81 μ m [.000150] THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m [.000050] THICK NICKEL UNDERPLATE
 SHIELD - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 3.0 μ m [.000120] MINIMUM THICK REFLOWED TIN
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- 3 DIMENSIONS MEASURED ALONG FRONT EDGES OF MATING FACE



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)



RECOMMENDED PANEL CUTOUT

YES	HIGH TEMP NYLON	5555141-3
NO	PBT POLYESTER	5555141-1
IR PROCESS COMPATIBLE	HOUSING MATERIAL	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN G GARRETT/L.A. MAYER	04APR2005	TE Connectivity
0 PLC ± -	1 PLC ± -	J. WESTMAN	04APR2005	
2 PLC ± 0.13[.005]	3 PLC ± -	S. FLICKINGER	04APR2005	NAME
4 PLC ± -	ANGLES ± -			MODULAR JACK ASSEMBLY, SHIELDED, 8 POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	PRODUCT SPEC	108-1163	APPLICATION SPEC
		SIZE	114-2048	RESTRICTED TO
		WEIGHT	A1 00779	SCALE 4:1
		CUSTOMER DRAWING	5555141	SHEET 1 OF 1
				REV B1